

**CLEAN VERSION OF PARTIAL SPECIFICATION**

**AND ALL PENDING CLAIMS**

**In the Specification:**

On page 1, lines 7-20, please replace the paragraphs as follows:

“This application is also related to the commonly assigned U.S. Patent Application No.: 09/782,185 entitled UNIQUE PROCESS CHEMISTRY FOR ETCHING ORGANIC LOW-K MATERIALS, by Helen H. Zhu, filed concurrently herewith and incorporated herein by reference.

This application is related to the commonly assigned U.S. Patent Application No.: 09/782,678 entitled POST-ETCH PHOTORESIST STRIP WITH O<sub>2</sub> AND NH<sub>3</sub> FOR ORGANOSILICATE GLASS LOW-K DIELECTRIC ETCH APPLICATIONS, by Rao V. Annapragada et al., filed concurrently herewith and incorporated herein by reference.

This application is also related to the commonly assigned U.S. Patent Application No.: 09/782,437 entitled USE OF HYDROCARBON ADDITION FOR THE ELIMINATION OF MICROMASKING DURING ETCHING OF ORGANIC LOW-K DIELECTRICS, by Chok W. Ho, filed concurrently herewith and incorporated herein by reference.”

**In the Claims:**

1. (Cancelled)

2. (Cancelled)

3. (Cancelled)